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DOCUMENT ID #: 90-100240

REVISION: A-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [F173A3F+2F] FC2QF

EFFECTIVE DATE: 11/28/2022

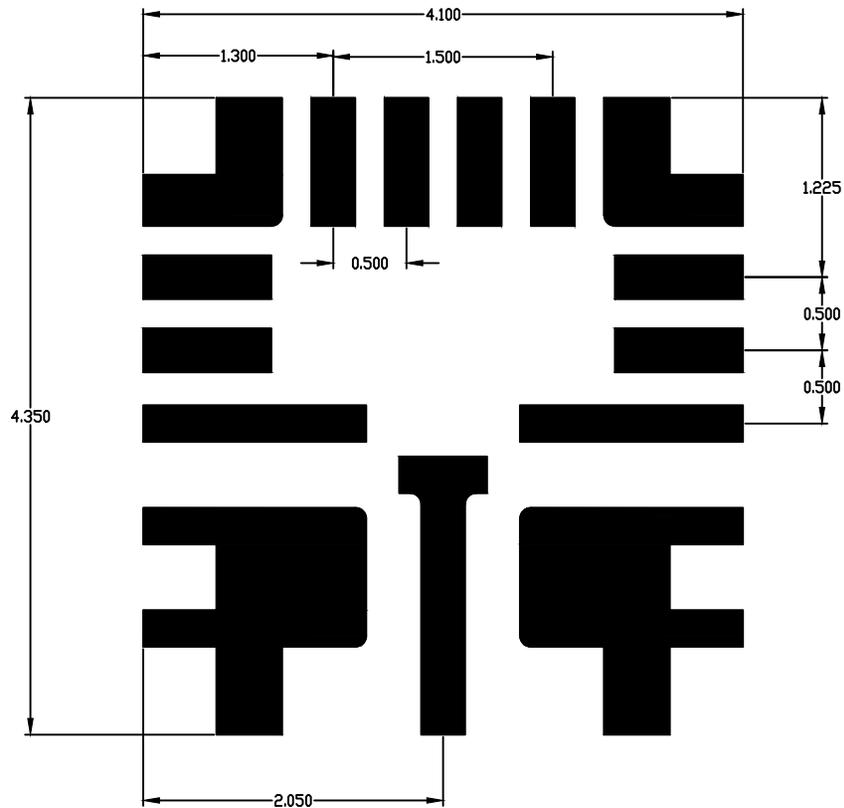
EXPIRATION DATE:

CHANGE NUMBER: 1176398

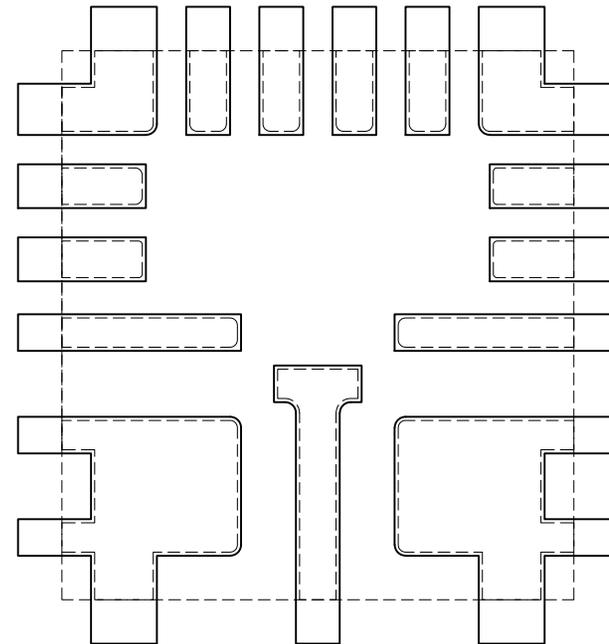
ORIGINATOR: Bernard Go

REASON FOR CHANGE:
INITIAL RELEASE

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100700
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

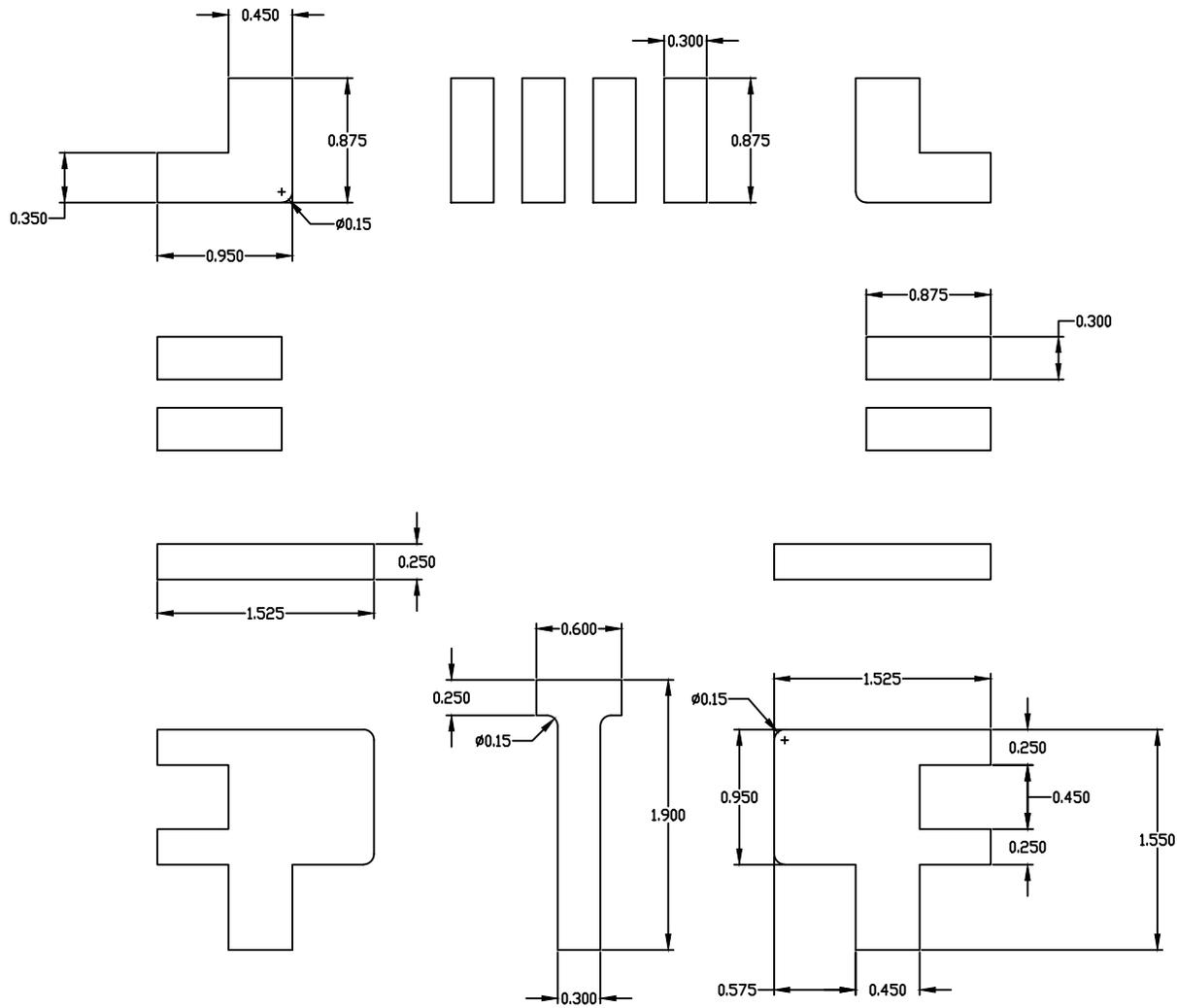
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This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maxim-ic.com/support> for further questions.

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PAD DETAILS



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